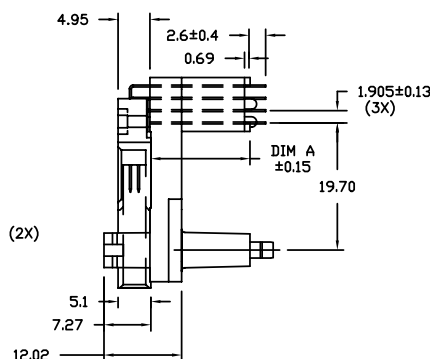
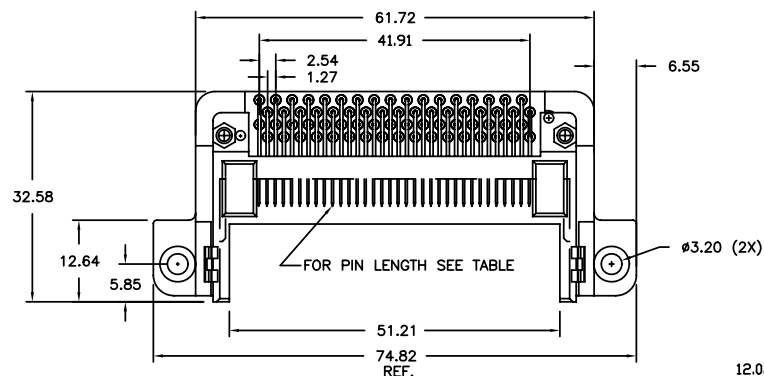
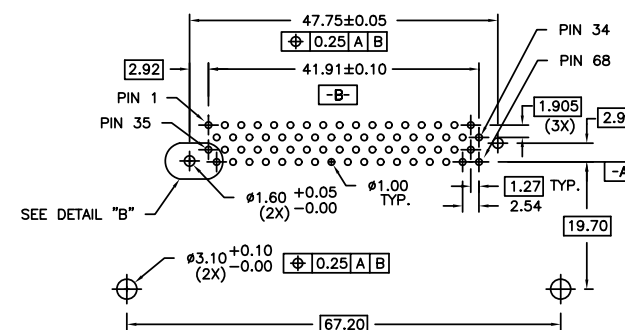
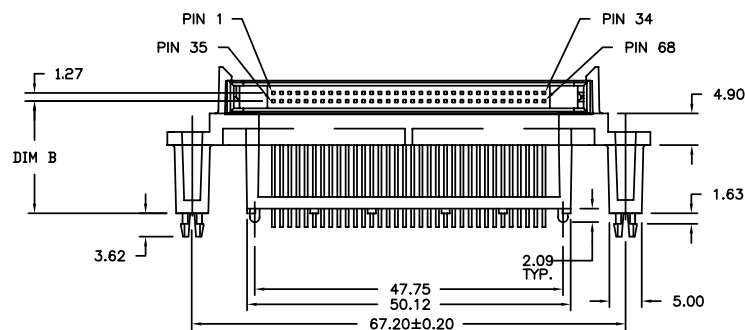
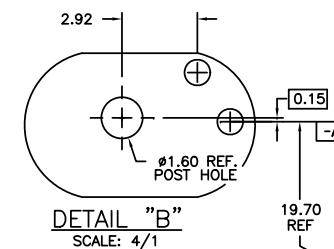


PRODUCT NO.	DIM "A"	DIM "B"
10036883-001	15.50	17.40
10036883-002	8.90	10.80
10036883-003	12.70	14.60
10036883-001LF	15.50	17.40
10036883-002LF	8.90	10.80
10036883-003LF	12.70	14.60



MATING PIN LENGTHS	
PIN POSITION	LENGTH
1,17,34,35,51,68	5.0 ± 0.1
ALL OTHERS	4.25 ± 0.1



NOTES:

- MATERIAL:
CONTACT - COPPER ALLOY
HEADER HOUSING - HIGH TEMPERATURE THERMOPLASTIC
STANDOFF - GLASS REINFORCED NYLON UL94V-0
- PLATING:
CONTACT - ALL OVER 0.5 μ m NICKEL UNDER PLATING
0.1 μ m GOLD OVER 0.5 μ m PALLADIUM
NICKEL SELECTIVE PLATING ON CONTACT.
2.5 μ m TIN/LEAD PLATING ON SOLDER TAIL UNLESS LEAD FREE
LEAD FREE SOLDER TAIL PLATING 2 μ m (80U") MIN. MATTE TIN
OVER 1.27 μ m (50U") MIN. NICKEL UNDERPLATE
- MATING CONNECTOR TO MATE WITH 68 POS. RECEPTACLE.
- IF LEAD FREE P/N. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.60MM MINIMUM THICK CIRCUIT BOARD.
- IF LEAD FREE P/N. PACKAGING MEETS GS-14-920 SPECIFICATION
- LEAD FREE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCRIBED IN GS-22-008
- PRODUCT SPECIFICATION: 110-263

mat'l. code		surface	tolerance	projection	product family
ISD1302		ISD406	ISD1101		PCMCIA
ltr ecn nldr	date	tolerances unless otherwise specified	angle	scale	title
A	V03-1340 PJ 01/08/04	0.X ± 0.3		MM	HIGH RISE HEADER ASM WITH
B	N05-0044 DAI 03/30/05	0.XX ± 0.13			SPECIAL MATING PIN LENGTHS
C	ELX-N-007941 ZK 11/01/11	0.XXX ± 0.05		scale 1:1	
		dr P.JAYADEEP 01/08/04			dwg no
		engr D.HORCHLER 01/08/04			sheet 1 of 1 size
		chr D.HORCHLER 01/08/04			10036883 A4
		app'd D.HORCHLER 01/08/04			type Product Customer Drawing
sheet	revision	nc			
index	sheet	1			